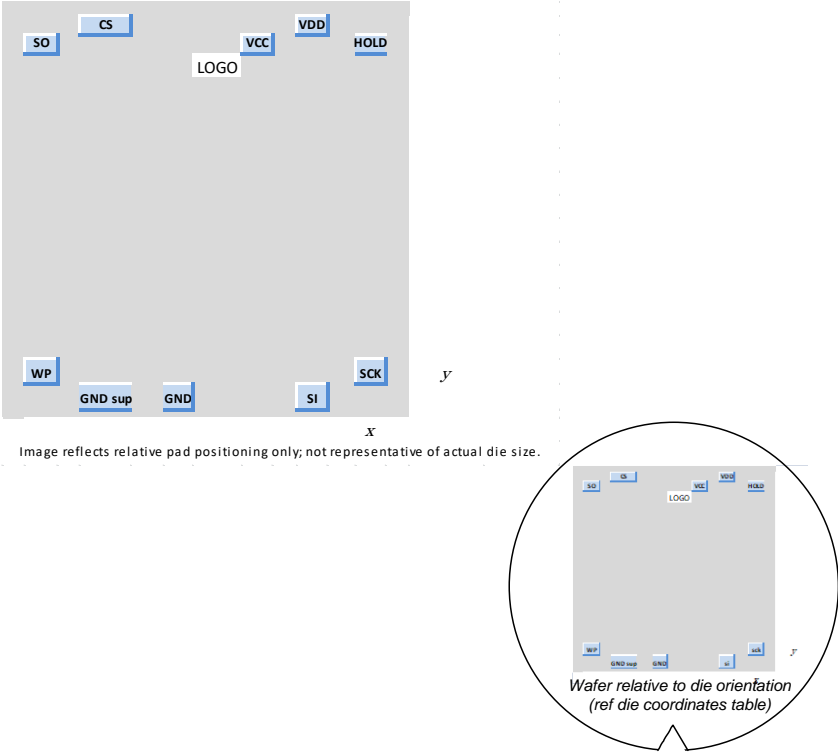


**WAFER PRODUCT DATASHEET (ADDENDUM)**

Product	AT25SF081-DWF																																															
Description	8Mbit, Standard Serial Flash, 2.5V – 3.6V VCC																																															
Die Map	 <p>Image reflects relative pad positioning only; not representative of actual die size.</p> <p>Wafer relative to die orientation (ref die coordinates table)</p>																																															
Die Size & Pad Coordinates	<table border="1"> <thead> <tr> <th></th> <th>X (μm)</th> <th>Y (μm)</th> </tr> </thead> <tbody> <tr> <td>Die Size</td> <td>1310</td> <td>1585</td> </tr> <tr> <td>Scribe Line Width</td> <td>60</td> <td>60</td> </tr> <tr> <td>Die Step</td> <td>1370</td> <td>1645</td> </tr> <tr> <td>Pad Opening</td> <td>65</td> <td>70</td> </tr> <tr> <td>CS</td> <td>217.9</td> <td>1525.7</td> </tr> <tr> <td>SO</td> <td>76.7</td> <td>1500.8</td> </tr> <tr> <td>WP</td> <td>54.2</td> <td>86.3</td> </tr> <tr> <td>GND SUP</td> <td>139.2</td> <td>63.7</td> </tr> <tr> <td>GND</td> <td>224.2</td> <td>63.7</td> </tr> <tr> <td>SI</td> <td>1118.4</td> <td>60.3</td> </tr> <tr> <td>SCK</td> <td>1241.9</td> <td>86.3</td> </tr> <tr> <td>HOLD</td> <td>1235.5</td> <td>1502.6</td> </tr> <tr> <td>VDD</td> <td>1136.3</td> <td>1525.3</td> </tr> <tr> <td>VCC</td> <td>1046.3</td> <td>1504.8</td> </tr> </tbody> </table>				X (μm)	Y (μm)	Die Size	1310	1585	Scribe Line Width	60	60	Die Step	1370	1645	Pad Opening	65	70	CS	217.9	1525.7	SO	76.7	1500.8	WP	54.2	86.3	GND SUP	139.2	63.7	GND	224.2	63.7	SI	1118.4	60.3	SCK	1241.9	86.3	HOLD	1235.5	1502.6	VDD	1136.3	1525.3	VCC	1046.3	1504.8
	X (μm)	Y (μm)																																														
Die Size	1310	1585																																														
Scribe Line Width	60	60																																														
Die Step	1370	1645																																														
Pad Opening	65	70																																														
CS	217.9	1525.7																																														
SO	76.7	1500.8																																														
WP	54.2	86.3																																														
GND SUP	139.2	63.7																																														
GND	224.2	63.7																																														
SI	1118.4	60.3																																														
SCK	1241.9	86.3																																														
HOLD	1235.5	1502.6																																														
VDD	1136.3	1525.3																																														
VCC	1046.3	1504.8																																														

Technical Details	
Adesto Product Family	Standard Flash
Density	8 Mbit
Operating Vcc	2.5V - 3.6V
ESD	JESD22-A114
Delivery Option	Wafer- unsawn
Wafer Size (mm)	300 mm
Process Geometry (nm)	90 nm
Die ID	5404
Wafer Map	Electronic- text file
Manufacturing Facility	XMC
Wafer Thickness (µm) Maximum	800
Back Grind Options	None / Contact Adesto
Back Plane Connection	Floating / Not Required
Backside preparation / metallization	None
Bond wire qualified	AU <input checked="" type="checkbox"/> CU <input type="checkbox"/> AG <input type="checkbox"/>
Passivation Material	PETEOS + SiON
Passivation Thickness (Å)	11000
Bond Pad Material	TaN/AlCu
Bond Pad Thickness (Å)	10300
Good Die per Wafer	<a href="#">Contact Adesto</a> <sup>1</sup>
Active Circuits underneath the bond pad	Yes

<sup>1</sup> Average value; subject to change without notice.

Part Number Ordering Code	Operating Temperature Range	Functional Specification
AT25SF081-DWF	-40°C to 85°C	<a href="http://www.adestotech.com/wp-content/uploads/DS-AT25SF081_045.pdf">http://www.adestotech.com/wp-content/uploads/DS-AT25SF081_045.pdf</a>

Revision Level – Release Date	History
A – September 2015	Initial release.
B – August 2017	Updated address and contact information.

**Adesto Technologies Corporation**

3600 Peterson Way, Santa Clara, CA 95054 | phone: (408) 400-0578 fax: (408) 400-0721 | www.adestotech.com

©2017 Adesto Technologies. All rights reserved. Adesto, the Adesto logo & CBRAM are trademarks of Adesto Technologies Corporation.

**Disclaimer:** Adesto Technologies Corporation makes no warranty for the use of its products, other than those expressly contained in the Company's standard warranty which is detailed in Adesto's Terms and Conditions located on the Company's web site. The Company assumes no responsibility for any errors which may appear in this document, reserves the right to change devices or specifications detailed herein at any time without notice, and does not make any commitment to update the information contained herein. No licenses to patents or other intellectual property of Adesto are granted by the Company in connection with the sale of Adesto products, expressly or by implication. Adesto's products are not authorized for use as critical components in life support devices or systems.